

1.MATERIAL SPECIFICATION:

NOTE:

1. MATERIAL,  
HOUSING: HIGH TEMP PLASTIC, UL94-V0, BLACK  
TERMINAL: COPPER ALLOY, SQ=0.40±0.03MM
2. FINISH:  
TERMINAL: GOLD AT CONTACT,  
G/F OVER 1um(40u")MIN Ni OVER ALL
3. SPEC.:  
PRODUCT SPEC: GS-12-629  
PACKING SPEC: GS-14-1420
4. THE HSG. WILL WITHSTAND EXPOSURE TO 260C  
PEAK TEMP. FOR 5 SEC. IN A WAVE SOLDER APPLICATION  
WITH A PCB.
5. PRODUCT NUMBERING:

20021511 - 0 0 0 XX X X LF

LEAD FREE

PLATING:

- 1: GOLD FLASH ALL OVER
- 4: 0.25um(10U")GOLD AT CONTACT
- 8: 0.76um(30U")GOLD AT CONTACT
- 9: 1u" GOLD OVER 30u" PdNi AT CONTACT

PACKING

T: TUBE

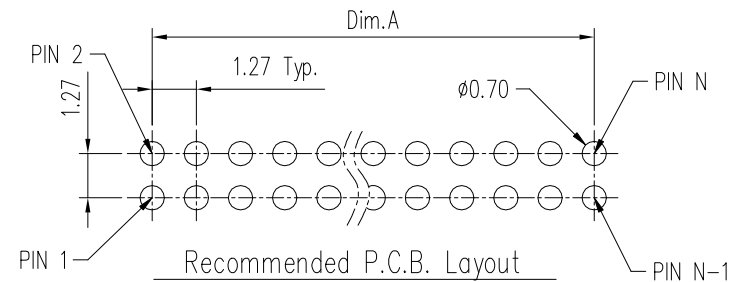
PIN COUNT

SEE TABLE 1

PIN LENGTH (Dim.C)

0= 2.70mm

1= 3.00mm



Recommended P.C.B. Layout  
Layout Tolerance = ± 0.05 mm

TABLE 1 ,DIM INFORMATION

DASH No.	Dim.	Amount of Pins	Dim.A	Dim.B
-000 06 XX LF	06	06	2.54	10.11
-000 08 XX LF	10	10	3.81	11.38
-000 10 XX LF	10	10	5.08	12.65
-000 12 XX LF	12	12	6.35	13.92
-000 14 XX LF	14	14	7.62	15.19
-000 16 XX LF	16	16	8.89	16.46
-000 20 XX LF	20	20	11.43	19.00
-000 26 XX LF	26	26	15.24	22.81
-000 30 XX LF	30	30	17.78	25.35

DASH No.	Dim.	Amount of Pins	Dim.A	Dim.B
-000 34 XX LF	34	34	20.32	27.89
-000 40 XX LF	40	40	24.13	31.70
-000 44 XX LF	44	44	26.67	34.24
-000 50 XX LF	50	50	30.48	38.05
-000 60 XX LF	60	60	36.83	44.40
-000 64 XX LF	64	64	39.37	46.94
-000 68 XX LF	68	68	41.91	49.48
-000 80 XX LF	80	80	49.53	57.10
-000 A0 XX LF	100	100	62.23	69.80

mat'l. code		surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection		product family	
ltr		ecn no		dr		date		HPL 585	
C		ELX-N-010362		ZK		01/06/12		title	
C3		-		YY		12/20/21		1.27X1.27MM BTB HEADER	
								SHROUDED VERTICAL TH	
								dwg no	
								sheet 1 of 1	
								size	
								20021511	
								A3	
								type	
								Product Customer Drawing	
sheet index		revision sheet							